

**Description**

The JSM130P06B uses advanced trench technology and design to provide excellent  $R_{DS(ON)}$  with low gate charge. This device is well suited for high current load applications.

**General Features**

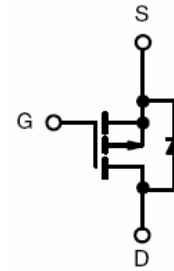
- $V_{DS} = -60V, I_D = -130A$   
 $R_{DS(ON)} < 13m\Omega @ V_{GS} = -10V$   
 $R_{DS(ON)} < 16m\Omega @ V_{GS} = -4.5V$
- High density cell design for ultra low  $R_{dson}$
- Fully characterized avalanche voltage and current
- Good stability and uniformity with high  $E_{AS}$
- Excellent package for good heat dissipation

**Application**

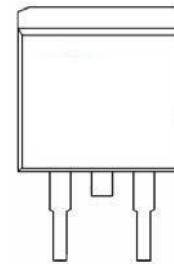
- Load switch

**100% UIS TESTED!**

**100%  $\Delta V_{ds}$  TESTED!**



Schematic diagram



pin assignment



TO-263-2L top view

**Package Marking and Ordering Information**

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
JSM130P06B	JSM130P06B	TO-263-2L	-	-	-

**Absolute Maximum Ratings ( $T_C = 25^\circ C$  unless otherwise noted)**

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	$V_{DS}$	-60	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Drain Current-Continuous	$I_D$	-130	A
Drain Current-Continuous( $T_C = 100^\circ C$ )	$I_D(100^\circ C)$	-58	A
Pulsed Drain Current	$I_{DM}$	-328	A
Maximum Power Dissipation	$P_D$	150	W
Derating factor		1.0	W/ $^\circ C$
Single pulse avalanche energy <sup>(Note 5)</sup>	$E_{AS}$	722	mJ
Operating Junction and Storage Temperature Range	$T_J, T_{STG}$	-55 To 175	$^\circ C$

**Thermal Characteristic**

Thermal Resistance, Junction-to-Case <sup>(Note 2)</sup>	$R_{\theta JC}$	1.0	$^\circ C/W$
--	-----------------	-----	--------------

**Electrical Characteristics (T<sub>C</sub>=25°C unless otherwise noted)**

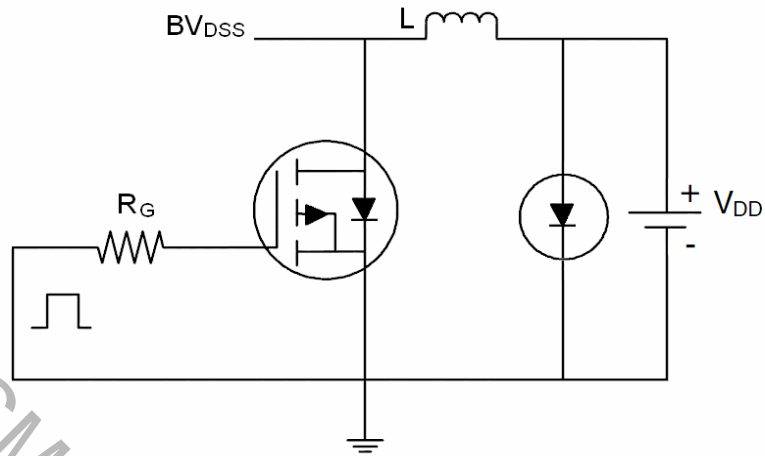
Parameter	Symbol	Condition	Min	Typ	Max	Unit
<b>Off Characteristics</b>						
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0V, I <sub>D</sub> =-250μA	-60	-	-	V
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> =-60V, V <sub>GS</sub> =0V	-	-	-1	μA
Gate-Body Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V	-	-	±100	nA
<b>On Characteristics</b> (Note 3)						
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =-250μA	-1.2	-1.8	-2.4	V
Drain-Source On-State Resistance	R <sub>DS(ON)</sub>	V <sub>GS</sub> =-10V, I <sub>D</sub> =-20A	-	11	13	mΩ
		V <sub>GS</sub> =-4.5V, I <sub>D</sub> =-20A	-	13	16	mΩ
Forward Transconductance	g <sub>FS</sub>	V <sub>DS</sub> =-5V, I <sub>D</sub> =-20A	-	25	-	S
<b>Dynamic Characteristics</b> (Note 4)						
Input Capacitance	C <sub>iss</sub>	V <sub>DS</sub> =-30V, V <sub>GS</sub> =0V, F=1.0MHz	-	5604	-	PF
Output Capacitance	C <sub>oss</sub>		-	356	-	PF
Reverse Transfer Capacitance	C <sub>rss</sub>		-	265	-	PF
<b>Switching Characteristics</b> (Note 4)						
Turn-on Delay Time	t <sub>d(on)</sub>	V <sub>DD</sub> =-30V, R <sub>L</sub> =1.5Ω, V <sub>GS</sub> =-10V, R <sub>G</sub> =3Ω	-	18	-	nS
Turn-on Rise Time	t <sub>r</sub>		-	20	-	nS
Turn-Off Delay Time	t <sub>d(off)</sub>		-	55	-	nS
Turn-Off Fall Time	t <sub>f</sub>		-	35	-	nS
Total Gate Charge	Q <sub>g</sub>	V <sub>DS</sub> =-30V, I <sub>D</sub> =-20A, V <sub>GS</sub> =-10V	-	62.1	-	nC
Gate-Source Charge	Q <sub>gs</sub>		-	9.3	-	nC
Gate-Drain Charge	Q <sub>gd</sub>		-	16.8	-	nC
<b>Drain-Source Diode Characteristics</b>						
Diode Forward Voltage	V <sub>SD</sub>	V <sub>GS</sub> =0V, I <sub>S</sub> =-20A	-	-	-1.2	V
Diode Forward Current	I <sub>S</sub>		-	-	-82	A
Reverse Recovery Time	t <sub>rr</sub>	T <sub>J</sub> = 25°C, I <sub>F</sub> = -20A	-	49	-	nS
Reverse Recovery Charge	Q <sub>rr</sub>	di/dt = -100A/μs (Note 3)	-	71	-	nC
Forward Turn-On Time	t <sub>on</sub>	Intrinsic turn-on time is negligible (turn-on is dominated by LS+LD)				

**Notes:**

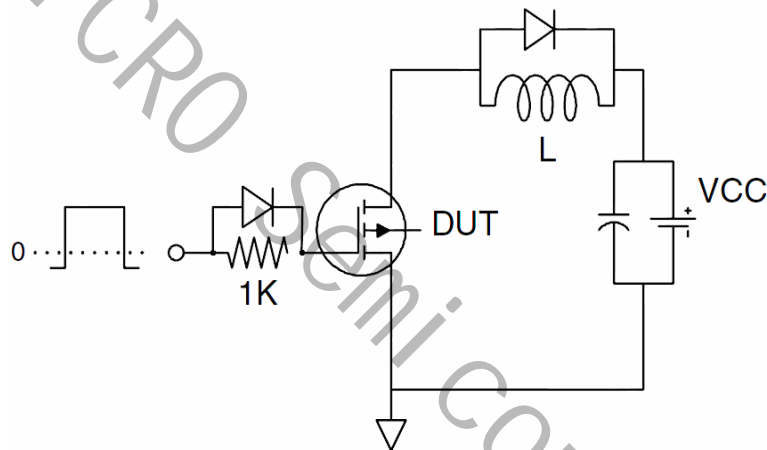
1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. Surface Mounted on FR4 Board, t ≤ 10 sec.
3. Pulse Test: Pulse Width ≤ 300μs, Duty Cycle ≤ 2%.
4. Guaranteed by design, not subject to production
5. E<sub>AS</sub> condition: T<sub>J</sub>=25°C, V<sub>DD</sub>=-30V, V<sub>G</sub>=-10V, L=0.5mH, R<sub>G</sub>=25Ω

**Test Circuit**

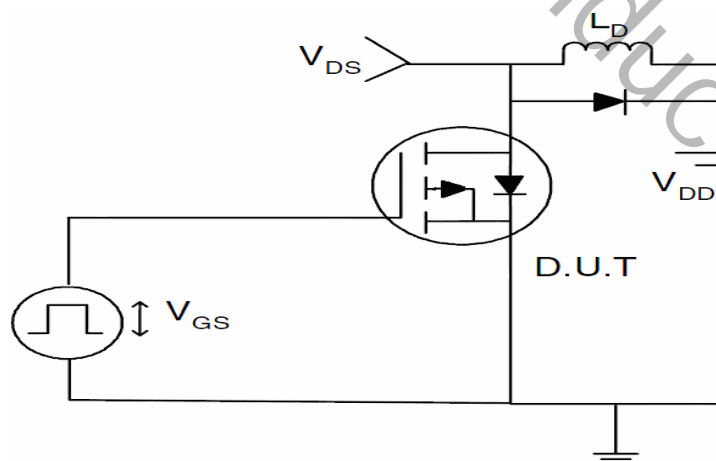
**1)  $E_{AS}$  Test Circuit**

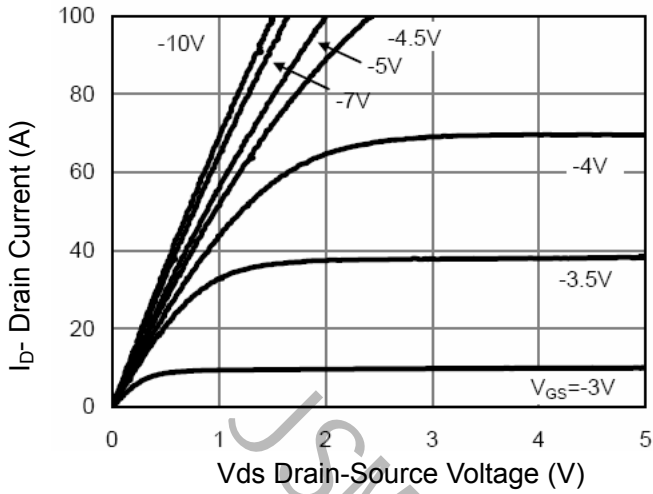
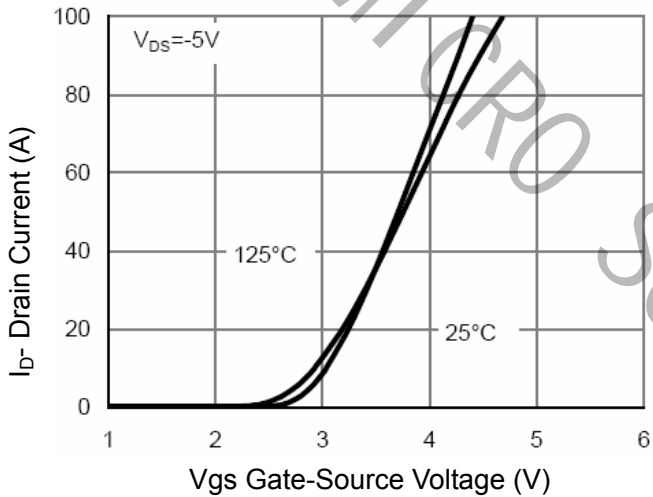
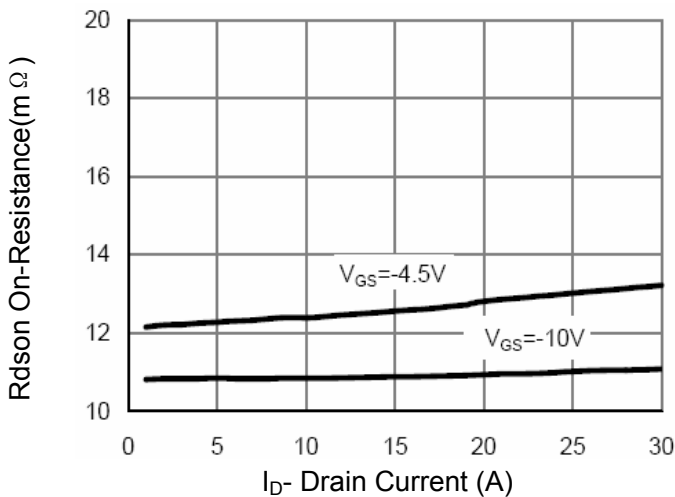
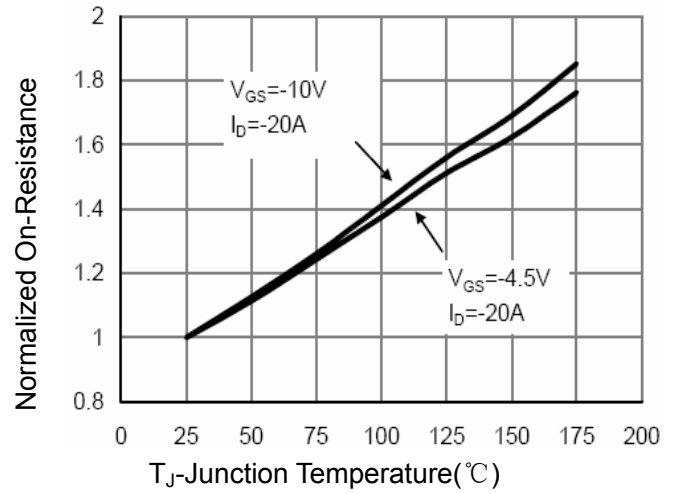
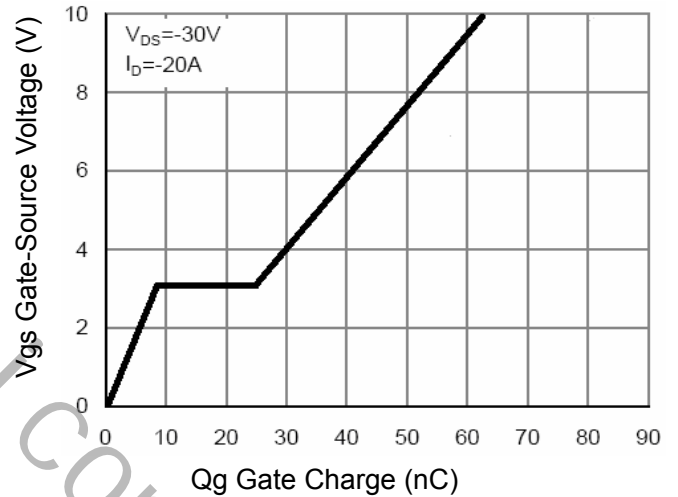
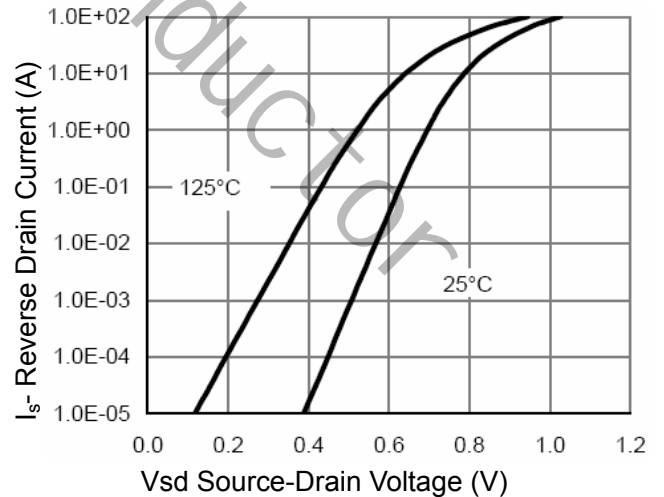


**2) Gate Charge Test Circuit**



**3) Switch Time Test Circuit**



**Typical Electrical and Thermal Characteristics (Curves)**

**Figure 1 Output Characteristics**

**Figure 2 Transfer Characteristics**

**Figure 3  $R_{DS(on)}$ - Drain Current**

**Figure 4  $R_{DS(on)}$ -Junction Temperature**

**Figure 5 Gate Charge**

**Figure 6 Source- Drain Diode Forward**

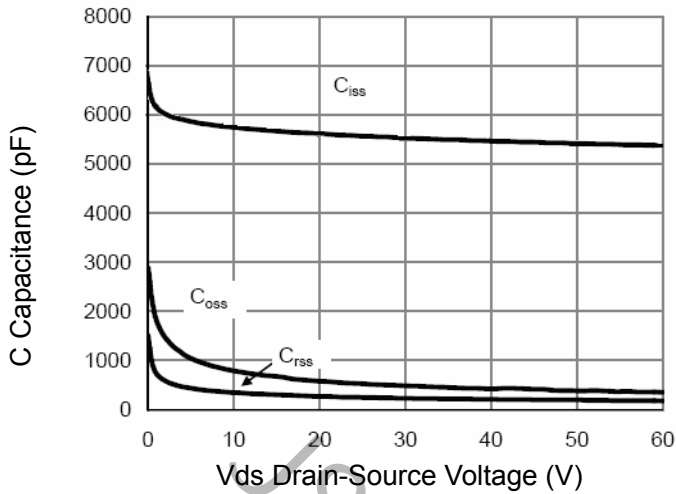


Figure 7 Capacitance vs Vds

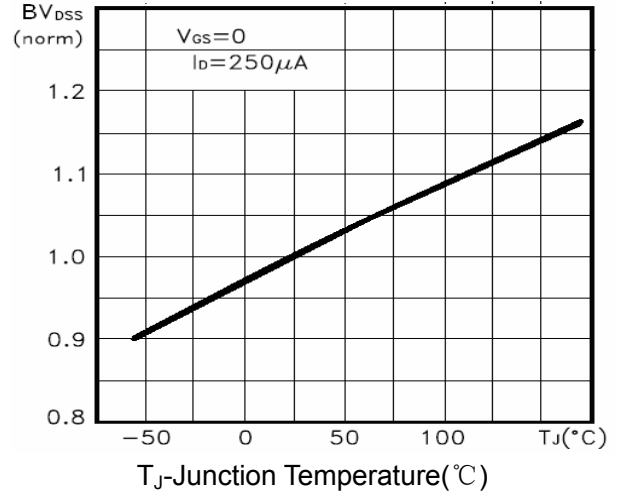


Figure 9  $BV_{DSS}$  vs Junction Temperature

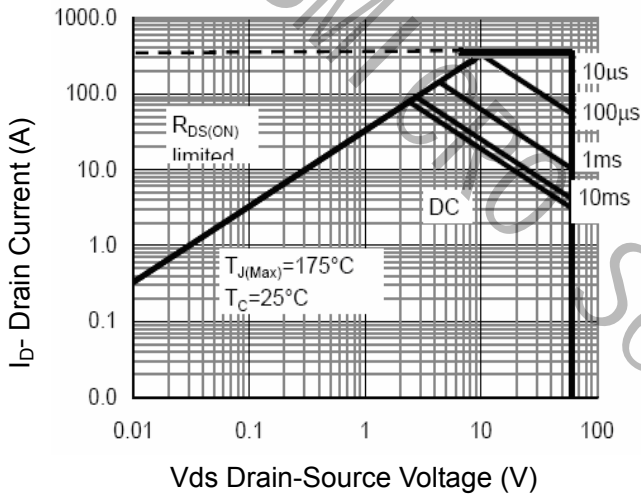


Figure 8 Safe Operation Area

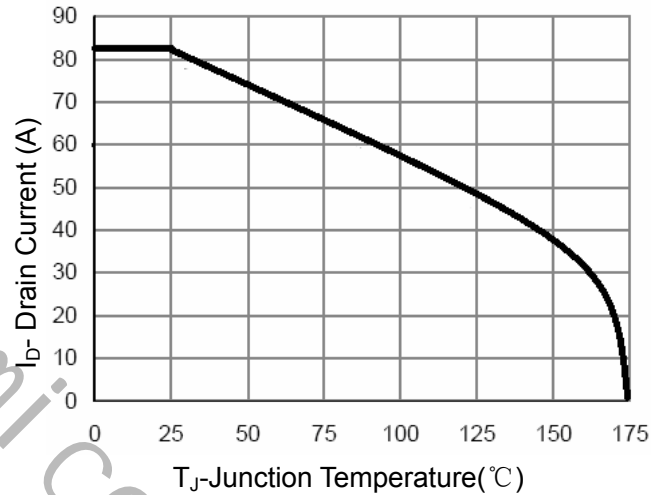


Figure 10  $I_D$  Current Derating vs Junction Temperature

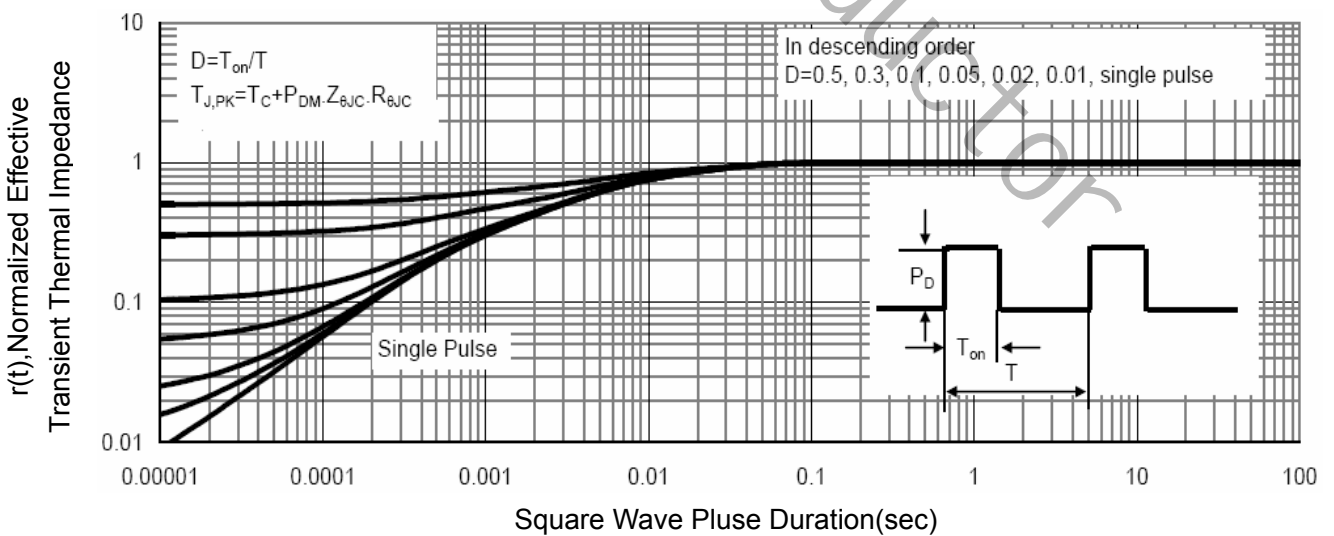


Figure 11 Normalized Maximum Transient Thermal Impedance

**TO-263-2L Package Information**
